L Number	Hits	Search Text	DB	Time stamp
_	28		USPAT	2004/09/22 14:56
-	2	"63122150"	EPO; JPO; DERWENT; IBM TDB	2004/03/31 16:51
_	6	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable) and (al or aluminum) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 15:20
_	6	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/31 17:00
-	15	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 15:20
_	9	<pre>((chip or die or ic or (integrated adj circuit)) and (fuse with cuttable) ) not ((chip or die or ic or (integrated adj circuit)) and (fuse with cuttable) and</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/31 16:56
<b>_</b>	8	substrate) (chip or die or ic or (integrated adj circuit)) and (fuse same cuttable) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/31 17:05
-	2	((chip or die or ic or (integrated adj circuit)) and (fuse same cuttable) and substrate) not ((chip or die or ic or (integrated adj circuit)) and (fuse with	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/31 17:00
_	13122	cuttable) ) (chip or die or ic or (integrated adj circuit)) and fuse and substrate	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/31 17:07
-	427	((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/22 15:20
	241	(((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)) and cut\$5	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 15:20
	1	(chip or die or ic or (integrated adj circuit)) and ((fuse or member or section) with cuttable) and (logic with series)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 15:07
_	4	(chip or die or ic or (integrated adj circuit)) and ((fuse or member or section) with cuttable) and (logic SAME series)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 15:07
_	7	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable) and (al or aluminum) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 15:20
_	16	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:20

-	267	circuit)) and fuse and substrate) and	USPAT; US-PGPUB;	2004/09/22 15:20
		(bonding adj pad)) and cut\$5	EPO; JPO; DERWENT;	
	469	((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and	IBM_TDB USPAT; US-PGPUB;	2004/09/22 15:21
		(bonding adj pad)	EPO; JPO; DERWENT;	
- ,	146	((((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)) and cut\$5) and logic	IBM_TDB USPAT; US-PGPUB;	2004/09/22 15:21
			EPO; JPO; DERWENT; IBM TDB	
_	218	(((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and	USPAT; US-PGPUB;	2004/09/22 15:23
		(bonding adj pad)) and logic	EPO; JPO; DERWENT; IBM TDB	
-	157	((((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and	USPAT; US-PGPUB;	2004/09/22 15:23
		(bonding adj pad)) and logic) and series	EPO; JPO; DERWENT; IBM TDB	
-	107	(((((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)) and cut\$5) and logic) and series	USPAT; US-PGPUB;	2004/09/22 15:29
			EPO; JPO; DERWENT; IBM TDB	
-	375	257/665.ccls.	USPAT; US-PGPUB;	2004/09/22 15:49
			EPO; JPO; DERWENT; IBM TDB	
-	375	257/528.ccls.	USPAT; US-PGPUB;	2004/09/22 15:50
			EPO; JPO; DERWENT; IBM TDB	
_	734	257/529.ccls.	USPAT; US-PGPUB;	2004/09/22 15:50
			EPO; JPO; DERWENT; IBM TDB	
_	.1324	257/777.ccls.	USPAT; US-PGPUB;	2004/09/22 17:31
			EPO; JPO; DERWENT; IBM TDB	
-	1762	257/784.ccls.	USPAT; US-PGPUB; EPO; JPO;	2004/09/22 15:50
			DERWENT; IBM_TDB	
-	1607	257/786.ccls.	USPĀT; US-PGPUB; EPO; JPO;	2004/09/22 17:31
			DERWENT; IBM_TDB	
-	1192	257/777.ccls. not 257/784.ccls.	USPAT; US-PGPUB; EPO; JPO;	2004/09/22 17:31
	1550	057/706	DERWENT; IBM_TDB	2004/00/00 17 01
	1553	257/786.ccls. not (257/777.ccls. not 257/784.ccls.)	USPAT; US-PGPUB; EPO; JPO;	2004/09/22 17:31
			DERWENT; IBM TDB	